

Appl. No.: 10/033,715
Amdt. Dated: 09/26/2005
Off. Act. Dated: 03/25/2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): A multilayer light emitting device, comprising:
a polysilicon electron emitting layer;
an amorphous insulating layer over the electron emitting layer; and
a direct bandgap light emitting layer over the insulating layer;
wherein electrons emitted from the electron emitting layer pass through the insulating layer and into the light emitting layer and are converted into bandgap radiation by the light emitting layer; and
wherein said electron emitting layer is formed with asperities that promote field emission of electrons into the insulating layer ~~without requiring formation of artificial emitter tips.~~
2. (canceled)
3. (original): A light emitting device as recited in claim 1, wherein said insulating layer comprises SiO₂.
4. (original): A light emitting device as recited in claim 1, wherein said light emitting layer comprises GaInP.
5. (original): A light emitting device as recited in claim 1, wherein said insulating layer and said electron emitting layer comprise in combination an oxidized polysilicon layer.

6. (currently amended): A multilayer light emitting device, comprising:
an oxidized polysilicon layer; and
a direct bandgap light emitting layer over said oxidized polysilicon layer;
wherein electrons emitted from the oxidized polysilicon layer are converted into
bandgap radiation by the light emitting layer; and
wherein said oxidized polysilicon layer is formed with asperities that promote field
emission of electrons ~~without requiring formation of artificial emitter tips.~~

7. (original): A light emitting device as recited in claim 6, wherein said light
emitting layer comprises GaInP.

8. (currently amended): A multilayer light emitting device, comprising:
an oxidized polysilicon layer; and
a GaInP layer over said oxidized polysilicon layer;
wherein said oxidized polysilicon layer is formed with asperities that promote field
emission of electrons ~~without requiring formation of artificial emitter tips.~~

9. (original): A light emitting device as recited in claim 8, wherein electrons
emitted from the oxidized polysilicon layer are converted into bandgap radiation by the
GaInP layer.

10. (currently amended): A multilayer light emitting device, comprising:
an oxidized polysilicon layer; and
a direct bandgap semiconductor layer over said oxidized polysilicon layer;
wherein said oxidized polysilicon layer is formed with asperities that promote field
emission of electrons ~~without requiring formation of artificial emitter tips.~~

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11. (original): A light emitting device as recited in claim 10, wherein electrons emitted from the oxidized polysilicon layer are converted into bandgap radiation by the direct bandgap layer.

12. (original): A light emitting device as recited in claim 11, wherein said direct bandgap layer comprises GaInP.

Claims 13-15 (canceled)

16. (previously presented): A light emitting panel comprising a plurality of devices as recited in claim 1, 6, 8, or 10 arranged in a mosaic array.

17. (currently amended): A method for generating light emission in a multilayer light emitting device, comprising:

injecting electrons from a polysilicon electron emitting layer through an insulating layer and into a direct bandgap light emitting layer where said electrons are converted into to bandgap radiation;

wherein said electron emitting layer comprises a material formed with asperities that promote field emission of electrons into said insulating layer ~~without requiring formation of artificial emitter tips.~~

18. (canceled)

19. (original): A method as recited in claim 17, wherein said insulating layer comprises SiO₂.

20. (original): A method as recited in claim 17, wherein said light emitting layer comprises GaInP.

21. (original): A method as recited in claim 17, wherein said insulating layer and said electron emitting layer comprise in combination an oxidized polysilicon layer.

22. (currently amended): A method for generating light emission in a multilayer light emitting device, comprising:

injecting electrons from an oxidized polysilicon layer into a direct bandgap light emitting layer where said electrons are converted into to bandgap radiation;

wherein said oxidized polysilicon layer is formed with asperities that promote field emission of electrons ~~without requiring formation of artificial emitter tips~~.

23. (original): A method as recited in claim 22, wherein said light emitting layer comprises GaInP.

24. (original): A method for generating light emission in a multilayer light emitting device, comprising:

injecting electrons from an oxidized polysilicon layer into a GaInP layer where said electrons are converted into to bandgap radiation.

25. (currently amended): A method for generating light emission in a multilayer light emitting device, comprising:

injecting electrons from an oxidized polysilicon layer into a direct bandgap semiconductor layer where said electrons are converted into to bandgap radiation;

wherein said electron emitting layer comprises a material formed with asperities that promote field emission of electrons into said insulating layer ~~without requiring formation of artificial emitter tips~~.

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26. (original): A method as recited in claim 25, wherein said direct bandgap layer comprises GaInP.

27. (currently amended): A method for generating light emission in a multilayer light emitting device, comprising:

injecting electrons from an oxidized polysilicon electron emitting layer into a GaInP layer where said electrons are converted into to bandgap radiation;

wherein said oxidized polysilicon layer is formed with asperities that promote field emission of electrons ~~without requiring formation of artificial emitter tips~~.

28. (original): A method as recited in claim 27, wherein said electron emitting layer comprises oxidized polysilicon.